

# MJD112 (NPN) MJD117 (PNP)

## Complementary Darlington Power Transistors

### DPAK For Surface Mount Applications

Designed for general purpose power and switching such as output or driver stages in applications such as switching regulators, converters, and power amplifiers.

#### Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Straight Lead Version in Plastic Sleeves (“-1” Suffix)
- Electrically Similar to Popular TIP31 and TIP32 Series
- Pb-Free Packages are Available

#### MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	$V_{CEO}$	100	Vdc
Collector-Base Voltage	$V_{CB}$	100	Vdc
Emitter-Base Voltage	$V_{EB}$	5	Vdc
Collector Current – Continuous – Peak	$I_C$	2 4	Adc
Base Current	$I_B$	50	mAdc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	20 0.16	W W/ $^\circ\text{C}$
Total Power Dissipation (Note1) @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	1.75 0.014	W W/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	-65 to +150	$^\circ\text{C}$

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	6.25	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	71.4	$^\circ\text{C}/\text{W}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. These ratings are applicable when surface mounted on the minimum pad sizes recommended.



ON Semiconductor®

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**SILICON  
POWER TRANSISTORS  
2 AMPERES  
100 VOLTS, 20 WATTS**

#### MARKING DIAGRAMS



A = Assembly Location  
Y = Year  
WW = Work Week  
x = 2 or 7  
G = Pb-Free Package

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

# MJD112 (NPN) MJD117 (PNP)

## ELECTRICAL CHARACTERISTICS ( $T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
<b>OFF CHARACTERISTICS</b>				
Collector-Emitter Sustaining Voltage (Note 2) ( $I_C = 30\text{ mA}$ , $I_B = 0$ )	$V_{CE(sus)}$	100	-	Vdc
Collector Cutoff Current ( $V_{CE} = 50\text{ Vdc}$ , $I_B = 0$ )	$I_{CEO}$	-	20	$\mu\text{Adc}$
Collector Cutoff Current ( $V_{CB} = 100\text{ Vdc}$ , $I_E = 0$ )	$I_{CBO}$	-	20	$\mu\text{Adc}$
Emitter Cutoff Current ( $V_{BE} = 5\text{ Vdc}$ , $I_C = 0$ )	$I_{EBO}$	-	2	mAdc
Collector-Cutoff Current ( $V_{CB} = 80\text{ Vdc}$ , $I_E = 0$ )	$I_{CBO}$	-	10	$\mu\text{Adc}$
Emitter-Cutoff Current ( $V_{BE} = 5\text{ Vdc}$ , $I_C = 0$ )	$I_{EBO}$	-	2	mAdc

## ON CHARACTERISTICS

DC Current Gain ( $I_C = 0.5\text{ Adc}$ , $V_{CE} = 3\text{ Vdc}$ ) ( $I_C = 2\text{ Adc}$ , $V_{CE} = 3\text{ Vdc}$ ) ( $I_C = 4\text{ Adc}$ , $V_{CE} = 3\text{ Vdc}$ )	$h_{FE}$	500 1000 200	- 12,000 -	-
Collector-Emitter Saturation Voltage ( $I_C = 2\text{ Adc}$ , $I_B = 8\text{ mAdc}$ ) ( $I_C = 4\text{ Adc}$ , $I_B = 40\text{ mAdc}$ )	$V_{CE(sat)}$	- -	2 3	Vdc
Base-Emitter Saturation Voltage ( $I_C = 4\text{ Adc}$ , $I_B = 40\text{ mAdc}$ )	$V_{BE(sat)}$	-	4	Vdc
Base-Emitter On Voltage ( $I_C = 2\text{ Adc}$ , $V_{CE} = 3\text{ Vdc}$ )	$V_{BE(on)}$	-	2.8	Vdc

## DYNAMIC CHARACTERISTICS

Current-Gain - Bandwidth Product ( $I_C = 0.75\text{ Adc}$ , $V_{CE} = 10\text{ Vdc}$ , $f = 1\text{ MHz}$ )	$f_T$	25	-	MHz
Output Capacitance ( $V_{CB} = 10\text{ Vdc}$ , $I_E = 0$ , $f = 0.1\text{ MHz}$ )	$C_{ob}$	- -	200 100	pF
	MJD117 MJD112			

2. Pulse Test: Pulse Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

\*These ratings are applicable when surface mounted on the minimum pad sizes recommended.

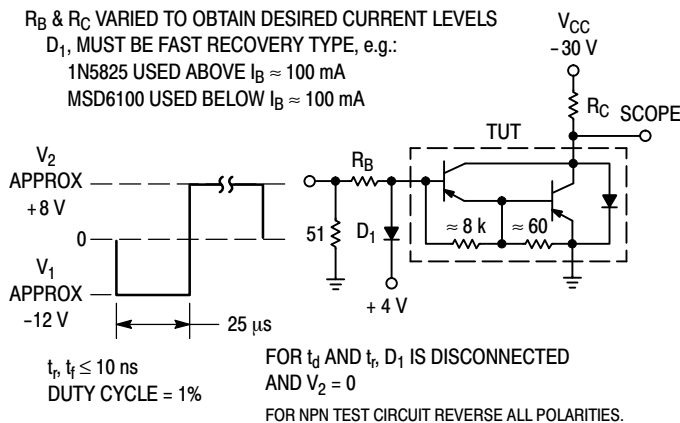


Figure 1. Switching Times Test Circuit

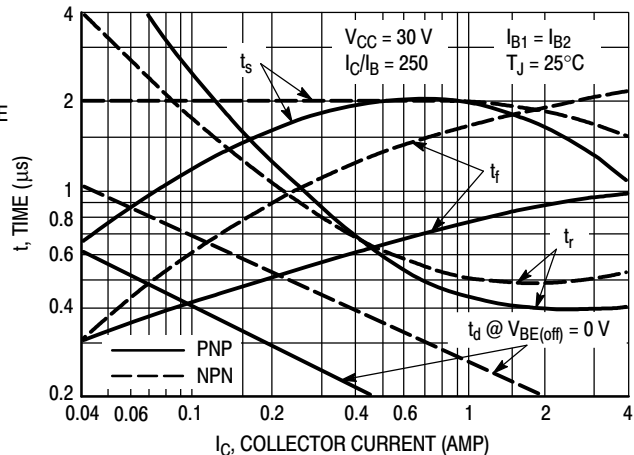


Figure 2. Switching Times

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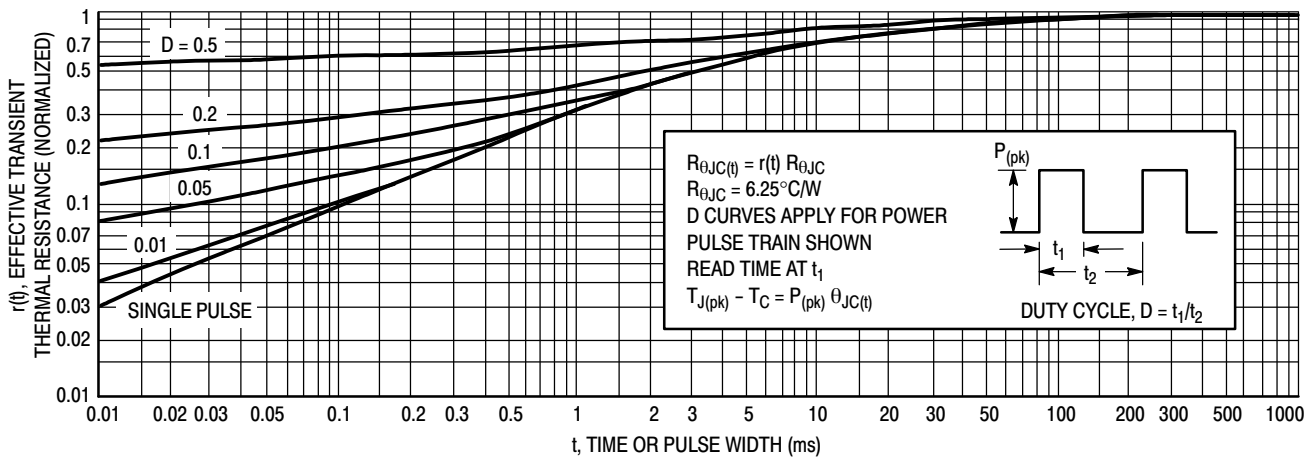


Figure 3. Thermal Response

## ACTIVE-REGION SAFE-OPERATING AREA

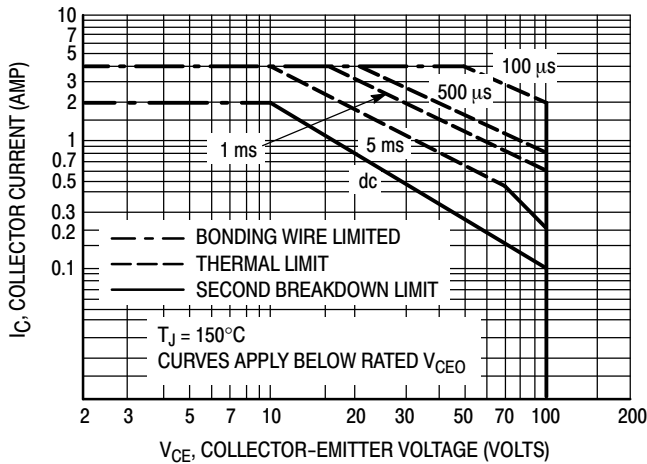


Figure 4. Maximum Rated Forward Biased Safe Operating Area

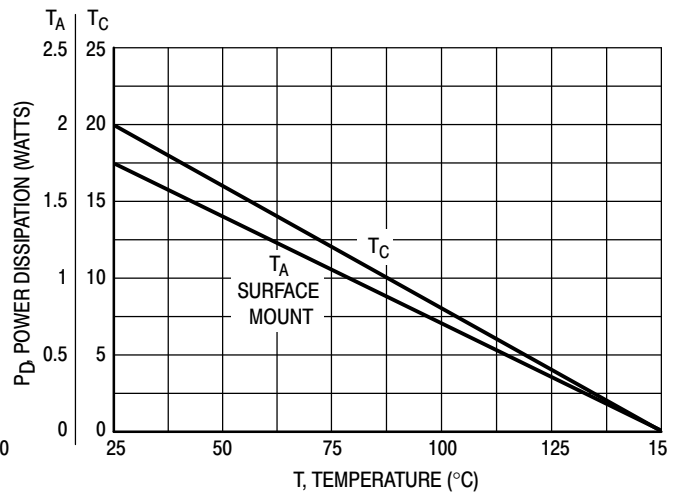


Figure 5. Power Derating

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figures 5 and 6 is based on  $T_{J(pk)} = 150^\circ\text{C}$ ;  $T_C$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} < 150^\circ\text{C}$ .  $T_{J(pk)}$  may be calculated from the data in Figure 4. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

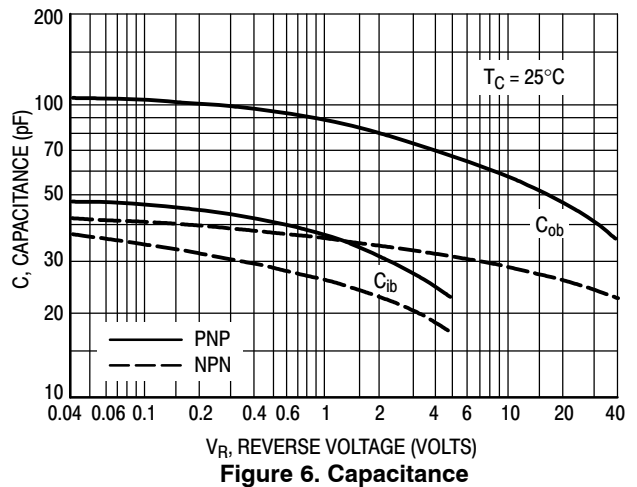


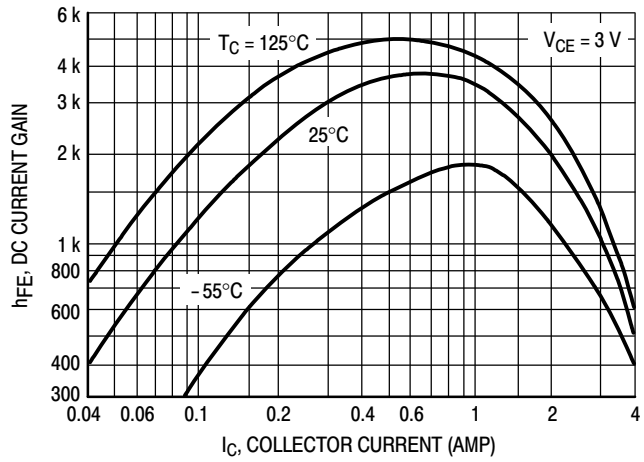
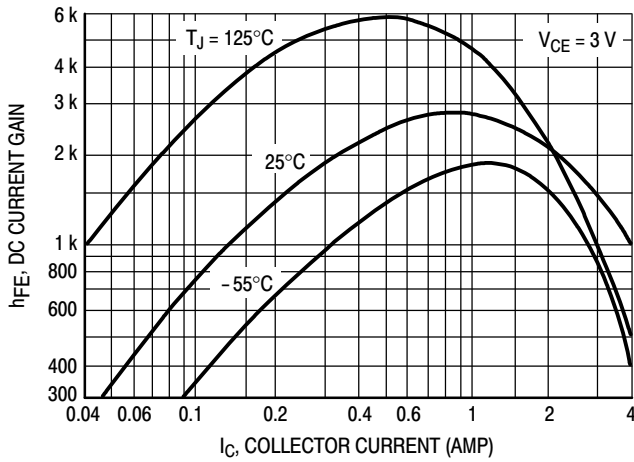
Figure 6. Capacitance

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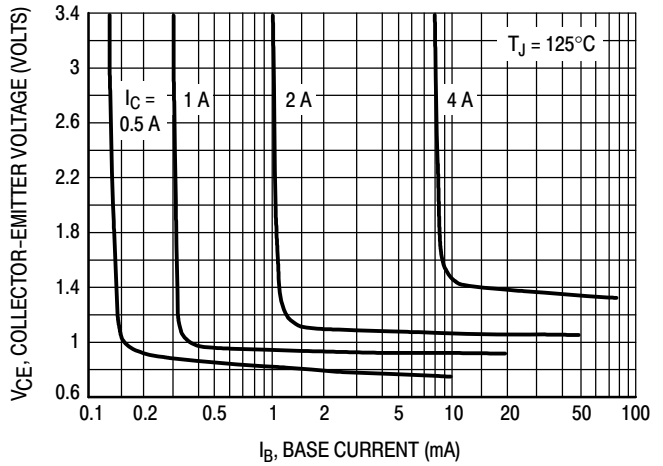
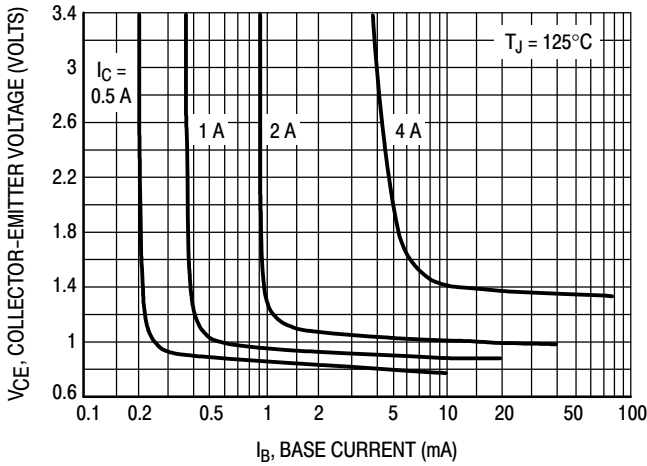
## TYPICAL ELECTRICAL CHARACTERISTICS

**NPN MJD112**

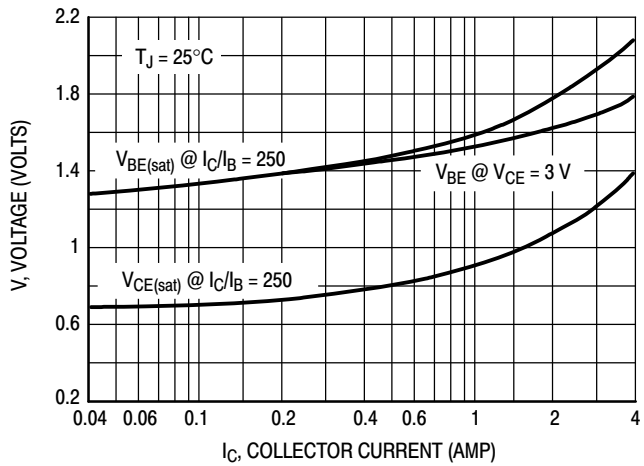
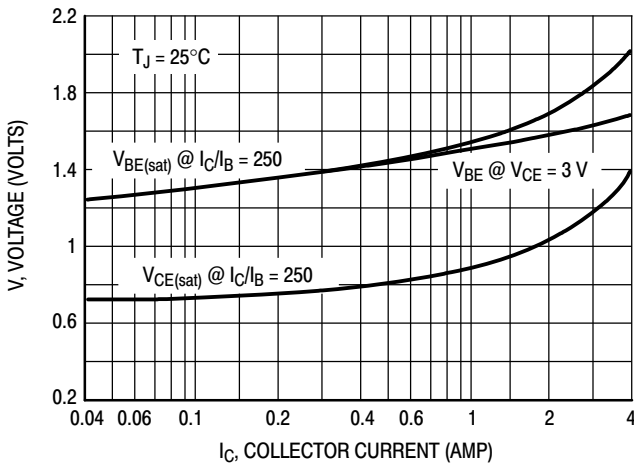
**PNP MJD117**



**Figure 7. DC Current Gain**



**Figure 8. Collector Saturation Region**

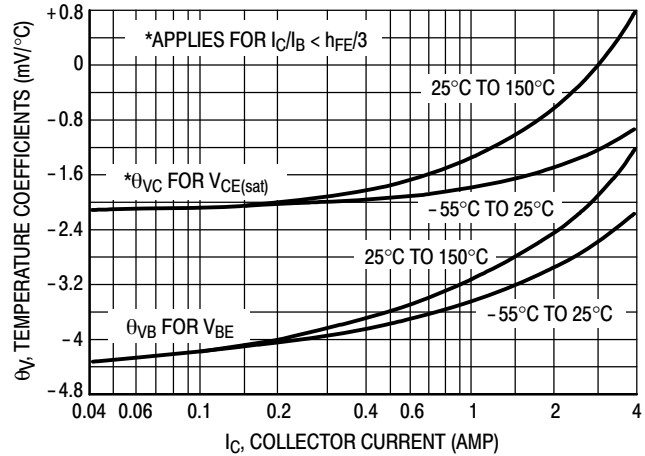
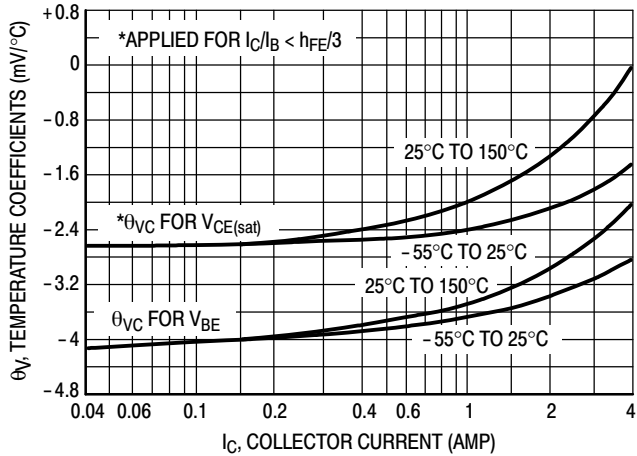


**Figure 9. "On Voltages"**

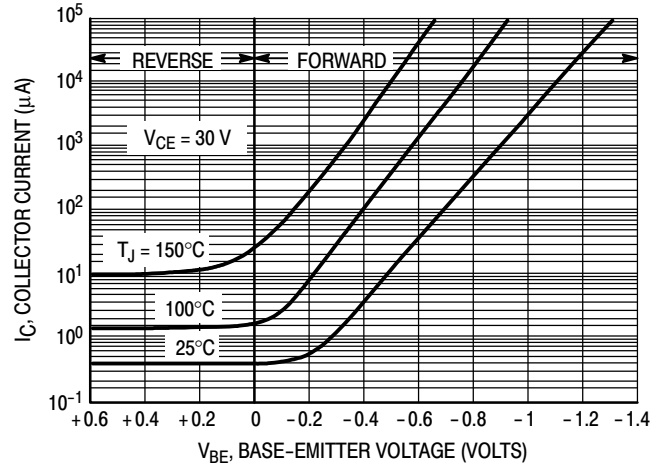
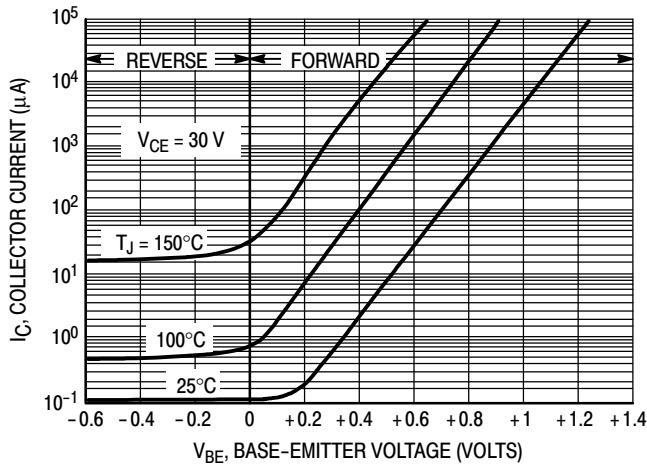
# MJD112 (NPN) MJD117 (PNP)

**NPN MJD112**

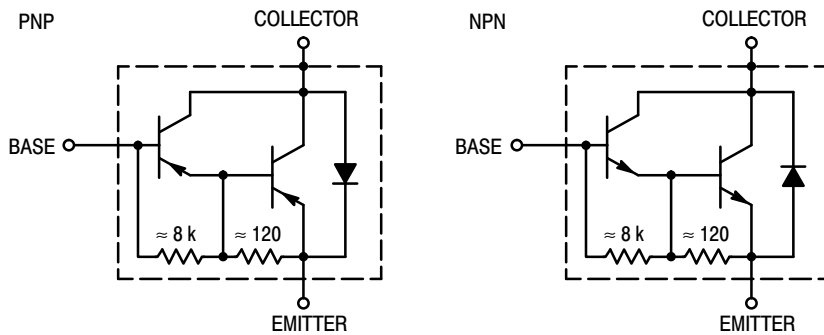
**PNP MJD117**



**Figure 10. Temperature Coefficients**



**Figure 11. Collector Cut-Off Region**



**Figure 12. Darlington Schematic**

## MJD112 (NPN) MJD117 (PNP)

### ORDERING INFORMATION

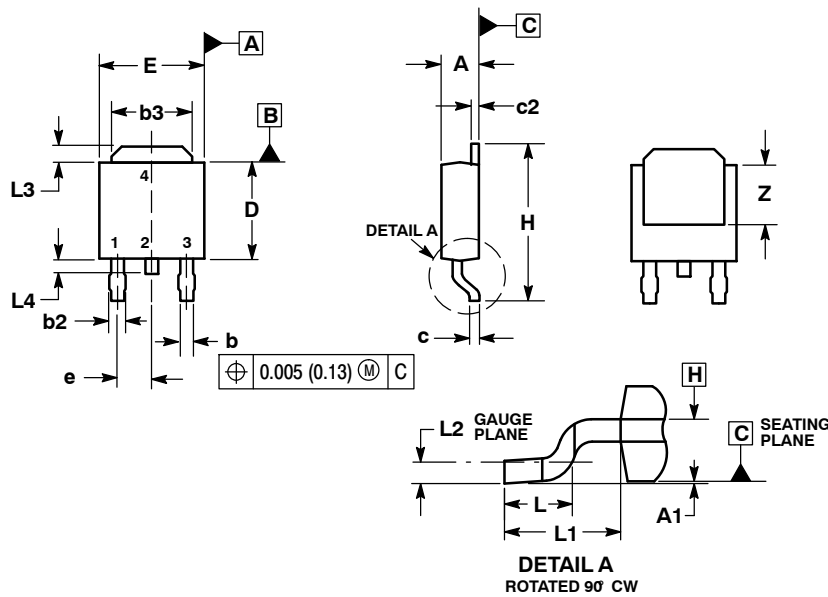
Device	Package Type	Package	Shipping†
MJD112	DPAK	369C	75 Units / Rail
MJD112G	DPAK (Pb-Free)		
MJD112-001	DPAK-3	369D	
MJD112-1G	DPAK-3 (Pb-Free)		
MJD112RL	DPAK	369C	1800 Tape & Reel
MJD112RLG	DPAK (Pb-Free)		2500 Tape & Reel
MJD112T4	DPAK		
MJD112T4G	DPAK (Pb-Free)		
MJD117	DPAK	369D	75 Units / Rail
MJD117G	DPAK (Pb-Free)		
MJD117-001	DPAK-3	369D	
MJD117-1G	DPAK-3 (Pb-Free)		
MJD117T4	DPAK	369C	2500 Tape & Reel
MJD117T4G	DPAK (Pb-Free)		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MJD112 (NPN) MJD117 (PNP)

## PACKAGE DIMENSIONS

### DPAK CASE 369C-01 ISSUE D



**NOTES:**

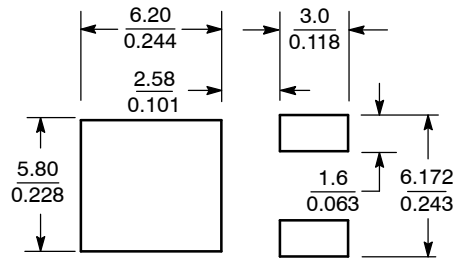
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090 BSC		2.29 BSC	
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108 REF		2.74 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4	---	0.040	---	1.01
Z	0.155	---	3.93	---

**STYLE 1:**

1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

### SOLDERING FOOTPRINT\*



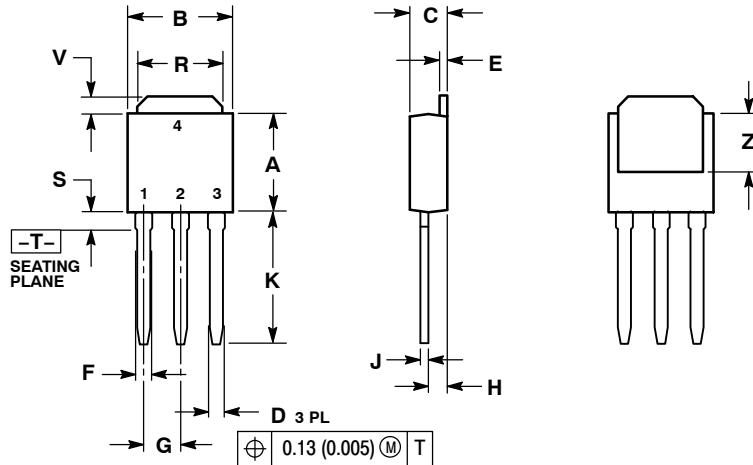
SCALE 3:1  $\left(\frac{\text{mm}}{\text{inches}}\right)$

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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## PACKAGE DIMENSIONS

DKPAK-3  
CASE 369D-01  
ISSUE B



### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.245	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.090 BSC		2.29 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.180	0.215	4.45	5.45
S	0.025	0.040	0.63	1.01
V	0.035	0.050	0.89	1.27
Z	0.155	---	3.93	---

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